



## PATENT ABSTRACTS OF JAPAN

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TANIGAWA SHIGEKI****(54) METHOD AND DEVICE FOR STICKING  
PROTECTIVE TAPE TO SEMICONDUCTOR  
WAFER**

(57) Abstract:

**PROBLEM TO BE SOLVED:** To provide a method for sticking a protective tape to a semiconductor wafer capable of suppressing the infiltration of polishing liquid and etching liquid from the boundary of a wafer surface and the protective tape, by sticking the protective tape on the inner side of the outer peripheral edge of the wafer without forming wrinkles or air bubbles in the protective tape stuck to the wafer.

**SOLUTION:** A positioned and supplied semiconductor wafer W is chucked and fixed on a mounting table 11, the protective tape T cut into a size and a shape matched with the outer shape of the semiconductor wafer W in a protective tape cutting part VI is chucked and held by a vacuum chuck table 49 vertically movable and swingable from the protective tape cutting part VI to the mounting table 11, the vacuum chuck table 49 is moved onto the mounting table 11 in a tilted state and the protective tape T is made to face right above the semiconductor wafer W. The part on a tilted lower side of the protective tape T is piled up on the semiconductor wafer W by lowering the table 49, the table 49 is horizontally

swung with the inclination lower side as a base point inside a vacuum atmosphere and thus, the entire adhesive surface of the protective tape T is press-fitted onto the semiconductor wafer W.

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